

Amendments to SpecificationPage 5, line 24 through page 6, line 10:

Instead of a vacuum or low thermal conductivity gas, the chamber 36 of Fig. 3 may contain a vacuum insulated panel (VIP) 59, as shown in Fig. 4. ~~VIPs~~ VIP is defined herein to consist of a filler material 60 called a "core" that is encapsulated in a barrier film 61, which may simply be plastic, or may be a plastic film which is sputter coated with thin metal film, or may be an aluminum or other metal thin film reinforced by plastic film laminations on each side. ~~The with the~~ barrier film ~~[[is]]~~ evacuated to a pressure between 0.001 Torr (0.0013mbar) and 1.0 Torr (1.3mbar), and thereafter sealed. The details of the VIP are irrelevant to the present invention, and may be chosen to suit any particular implementation thereof. The core may be thermal formed to the shape of the manifold prior to being encapsulated within the barrier film. The manifold may simply comprise the VIP 59 formed in the shape of a manifold, with a puncture resistant film attached to one or both sides of the VIP to provide enhanced structural integrity.

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Referring to Fig. 5, the insulation of a reactant gas manifold 14c may comprise a gas filled panel (GFP) 63. GFP is defined herein as ~~which uses~~ a high molecular weight, low thermal conductivity gas within a hermetic polymer film bag 64 to provide extraordinary thermal insulation. Within the essentially-hermetic barrier provided by the film 64, a cellular structure 65, called a baffle, is filled with the gas. Argon gas provides an effective thermal conductivity of 0.020 W/m<sup>°K</sup>, krypton gas provides a thermal conductivity of 0.012 W/m<sup>°K</sup>, and xenon gas provides a thermal conductivity of 0.007 W/m<sup>°K</sup>.